

September 2009

# H11N1M, H11N2M, H11N3M 6-Pin DIP High Speed Logic Optocouplers

#### **Features**

- High data rate, 5MHz typical (NRZ)
- Free from latch up and oscilliation throughout voltage and temperature ranges.
- Microprocessor compatible drive
- Logic compatible output sinks 16mA at 0.5V maximum
- Guaranteed on/off threshold hysteresis
- Wide supply voltage capability, compatible with all popular logic systems
- High common mode transient immunity, 2000V/µs minimum
- Fast switching  $t_r = 7.5$ ns typical,  $t_f = 12$ ns typical
- Underwriter Laboratory (UL) recognized—file #E90700
- VDE recognized—File#102497 Add option V (e.g., H11N1VM)

# **Applications**

- Logic to logic isolator
- Programmable current level sensor
- Line receiver—eliminate noise and transient problems
- A.C. to TTL conversion—square wave shaping
- Interfaces computers with peripherals
- Isolated power MOS driver for power supplies

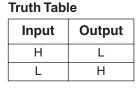
# **Description**

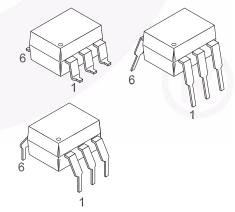
The H11NXM series has a high speed integrated circuit detector optically coupled to an AlGaAs infrared emitting diode. The output incorporates a Schmitt trigger, which provides hysteresis for noise immunity and pulse shaping. The detector circuit is optimized for simplicity of operation and utilizes an open collector output for maximum application flexibility.

#### **Schematic**

# ANODE 1 CATHODE 2 S GND 4 Vo

# Package Outlines





©2005 Fairchild Semiconductor Corporation H11N1M, H11N2M, H11N3M Rev. 1.0.2

# **Absolute Maximum Ratings** (T<sub>A</sub> = 25°C unless otherwise specified.)

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameters	Value	Units
TOTAL DEVIC	E		
T <sub>STG</sub>	Storage Temperature	-40 to +150	°C
T <sub>OPR</sub>	Operating Temperature	-40 to +85	°C
T <sub>SOL</sub>	Lead Solder Temperature	260 for 10 sec	°C
P <sub>D</sub>	Total Device Power Dissipation @ 25°C	250	mW
	Derate Above 25°C	2.94	mW/°C
EMITTER			
I <sub>F</sub>	Continuous Forward Current	30	mA
V <sub>R</sub>	Reverse Voltage	6	V
I <sub>F</sub> (pk)	Forward Current – Peak (1µs pulse, 300 pps)	1.0	Α
P <sub>D</sub>	LED Power Dissipation 25°C Ambient	120	mW
	Derate Linearly From 25°C	1.41	mW/°C
DETECTOR			
P <sub>D</sub>	Detector Power Dissipation @ 25°C	150	mW
	Derate Linearly from 25°C	1.76	mW/°C
V <sub>O</sub>	V <sub>45</sub> Allowed Range	0 to 16	V
V <sub>CC</sub>	V <sub>65</sub> Allowed Range	0 to 16	V
I <sub>O</sub>	I <sub>4</sub> Output Current	50	mA

# **Electrical Characteristics** (T<sub>A</sub> = 25°C unless otherwise specified.)

## **Individual Component Characteristics**

Symbol	Parameters	Test Conditions	Device	Min.	Тур.*	Max.	Units
EMITTER	EMITTER						
V <sub>F</sub>	Input Forward Voltage	I <sub>F</sub> = 10mA	All		1.4	2	V
		I <sub>F</sub> = 0.3mA		0.75	1.25		
I <sub>R</sub>	Reverse Current	V <sub>R</sub> = 5V	All			10	μA
СЈ	Capacitance	V = 0, f = 1.0MHz	All			100	pF
DETECTO	DETECTOR						
V <sub>CC</sub>	Operating Voltage Range		All	4		15	V
I <sub>CC(off)</sub>	Supply Current	I <sub>F</sub> = 0, V <sub>CC</sub> = 5V	All		6	10	mA
I <sub>OH</sub>	Output Current, High	$I_F = 0.3 \text{mA}, V_{CC} = V_O = 15 \text{V}$	All			100	μΑ

#### **Transfer Characteristics**

Symbol	DC Characteristics	Test Conditions	Device	Min.	Тур.*	Max.	Units
I <sub>CC(on)</sub>	Supply Current	I <sub>F</sub> = 10mA, V <sub>CC</sub> = 5V	All		6.5	10	mA
V <sub>OL</sub>	Output Voltage, Low	$R_L$ =270 $\Omega$ , $V_{CC}$ =5 $V$ ,	All	\\.		0.5	V
		$I_F = I_{F(on)} \text{ max.}$					
I <sub>F(on)</sub>	Turn-On Threshold Current	$R_L = 270\Omega, V_{CC} = 5V^{(1)}$	H11N1M	0.8		3.2	mA
			H11N2M	2.3		5	
			H11N3M	4.1		10	
I <sub>F(off)</sub>	Turn-Off Threshold Current	$R_L = 270\Omega, V_{CC} = 5V$	All	0.3			mA
I <sub>F(off)</sub> / I <sub>F(on)</sub>	Hysteresis Ratio	$R_L = 270\Omega, V_{CC} = 5V$	All	0.65		0.95	

#### **Switching Speed**

Symbol	AC Characteristics	Test Conditions	Device	Min.	Тур.*	Max.	Units
t <sub>PHL</sub>	Propagation Delay Time HIGH-to-LOW	C = 120pF, $t_P$ = 1 $\mu$ s, R <sub>E</sub> = <sup>(2)</sup> , Figure 1	All		100	330	ns
t <sub>r</sub>	Rise Time	C = 120pF, $t_P$ = 1 $\mu$ s, R <sub>E</sub> = <sup>(2)</sup> , Figure 1	All		7.5		ns
t <sub>PLH</sub>	Propagation Delay Time LOW-to-HIGH	C = 120pF, $t_P$ = 1 $\mu$ s, $R_E$ = <sup>(2)</sup> , Figure 1	All		150	330	ns
t <sub>f</sub>	Fall Time	C = 120pF, $t_P$ = 1 $\mu$ s, $R_E$ = <sup>(2)</sup> , Figure 1	All		12		ns
	Data Rate		All		5		MHz

#### **Isolation Characteristics**

Symbol	Parameters	Test Conditions	Min.	Тур.*	Max.	Units
V <sub>ISO</sub>	Input-Output Isolation Voltage	f = 60 Hz, t =1 sec.	7500			V <sub>PEAK</sub>
C <sub>ISO</sub>	Isolation Capacitance	V <sub>I-O</sub> = 0V, f = 1 MHz		0.4	0.6	pF
R <sub>ISO</sub>	Isolation Resistance	V <sub>I-O</sub> = ±500 VDC	10 <sup>11</sup>			Ω

<sup>\*</sup>Typical values at  $T_A = 25$ °C

#### Notes

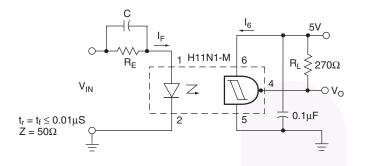
- Maximum I<sub>F(ON)</sub> is the maximum current required to trigger the output. For example, a 3.2mA maximum trigger current would require the LED to be driven at a current greater than 3.2mA to guarantee the device will turn on. A 10% guard band is recommended to account for degradation of the LED over its lifetime. The maximum allowable LED drive current is 30mA.
- 2. H11N1:  $R_{\rm E}$  = 910 $\Omega$ , H11N2:  $R_{\rm E}$  = 560 $\Omega$ , H11N3:  $R_{\rm E}$  = 240 $\Omega$

# **Safety and Insulation Ratings**

As per IEC 60747-5-2, this optocoupler is suitable for "safe electrical insulation" only within the safety limit data. Compliance with the safety ratings shall be ensured by means of protective circuits.

Symbol	Parameter	Min.	Тур.	Max.	Unit
	Installation Classifications per DIN VDE 0110/1.89 Table 1				
	For Rated Main Voltage < 150Vrms		I-IV		
	For Rated Main voltage < 300Vrms		I-IV		
	Climatic Classification		55/100/21		
	Pollution Degree (DIN VDE 0110/1.89)		2		
CTI	Comparative Tracking Index	175			
V <sub>PR</sub>	Input to Output Test Voltage, Method b, V <sub>IORM</sub> x 1.875 = V <sub>PR</sub> , 100% Production Test with tm = 1 sec, Partial Discharge < 5pC	1594			V <sub>peak</sub>
	Input to Output Test Voltage, Method a, V <sub>IORM</sub> x 1.5 = V <sub>PR</sub> , Type and Sample Test with tm = 60 sec, Partial Discharge < 5pC	1275			V <sub>peak</sub>
V <sub>IORM</sub>	Max. Working Insulation Voltage	850			V <sub>peak</sub>
$V_{IOTM}$	Highest Allowable Over Voltage	6000			V <sub>peak</sub>
	External Creepage	7			mm
	External Clearance	7			mm
	Insulation Thickness	0.5			mm
RIO	Insulation Resistance at Ts, V <sub>IO</sub> = 500V	10 <sup>9</sup>			Ω

# **Typical Performance Curves**



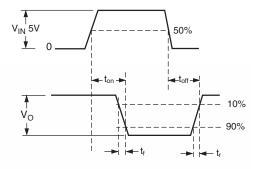
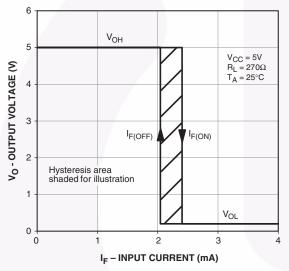


Figure 1. Switching Test Circuit and Waveforms

Figure 2. Transfer Characteristics



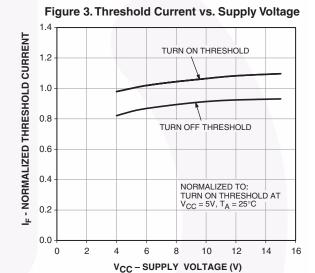


Figure 4. Threshold Current vs. Temperature

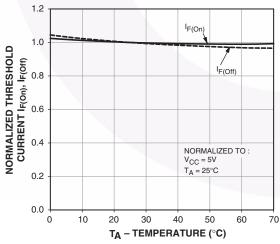
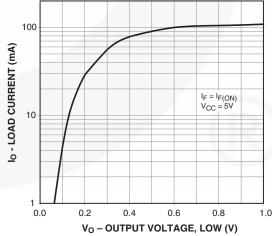


Figure 5. Load Current vs. Output Voltage



# **Typical Performance Curves** (Continued)

Figure 6. Supply Current vs. Supply Voltage

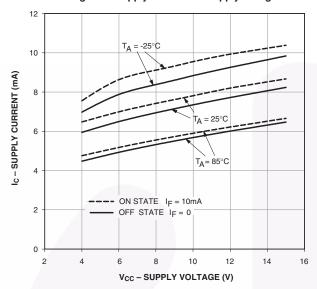
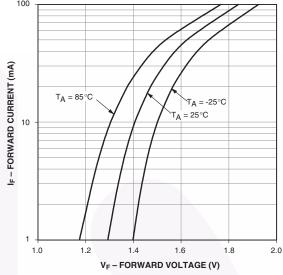
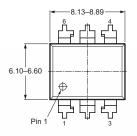


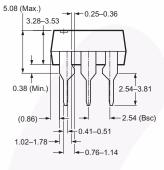
Figure 7. LED Forward Voltage vs. Forward Current

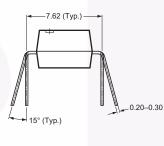


# **Package Dimensions**

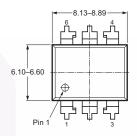
#### **Through Hole**

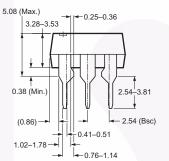


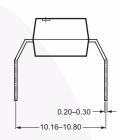




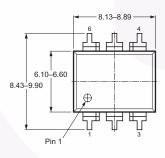
## 0.4" Lead Spacing

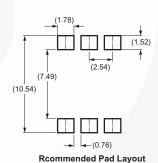


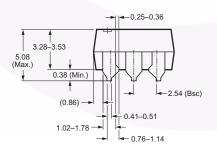


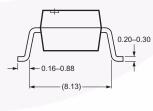


#### **Surface Mount**







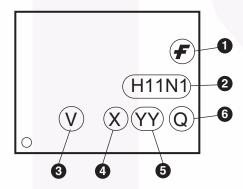


**Note:** All dimensions in mm.

# **Ordering Information**

Option	Order Entry Identifier (Example)	Description
No option	H11N1M	Standard Through Hole Device
S	H11N1SM	Surface Mount Lead Bend
SR2	H11N1SR2M	Surface Mount; Tape and Reel
Т	H11N1TM	0.4" Lead Spacing
V	H11N1VM	VDE 0884
TV	H11N1TVM	VDE 0884, 0.4" Lead Spacing
SV	H11N1SVM	VDE 0884, Surface Mount
SR2V	H11N1SR2VM	VDE 0884, Surface Mount, Tape and Reel

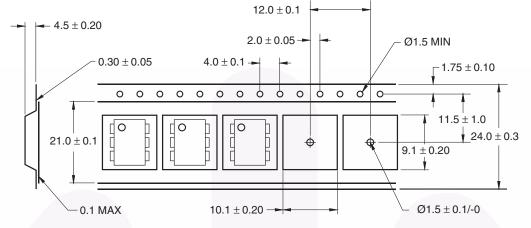
# **Marking Information**



Definiti	Definitions						
1	Fairchild logo						
2	Device number						
3	VDE mark (Note: Only appears on parts ordered with VDE option – See order entry table)						
4	One digit year code, e.g., '3'						
5	Two digit work week ranging from '01' to '53'						
6	Assembly package code						

<sup>\*</sup>Note – Parts that do not have the 'V' option (see definition 3 above) that are marked with date code '325' or earlier are marked in portrait format.

# **Tape Dimensions**

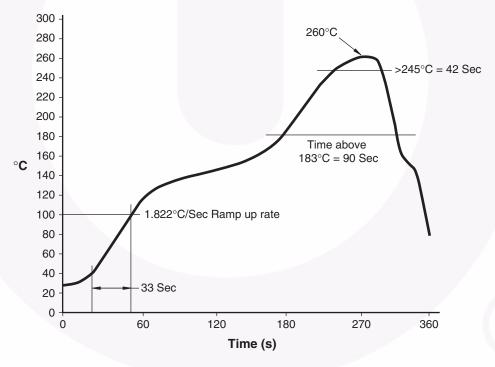


User Direction of Feed ----

#### Note:

All dimensions are in millimeters.

# **Reflow Soldering Profile**







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